

PS2915-1

R08DS0112EJ0201

Rev.2.01

HIGH CTR, AC INPUT RESPONSE TYPE 4-PIN ULTRA SMALL FLAT-LEAD PHOTOCOUPLER

Sep 27, 2019

DESCRIPTION

The PS2915-1 is an optically coupled isolator containing GaAs light emitting diodes and an NPN silicon phototransistor in one package for high density mounting applications.

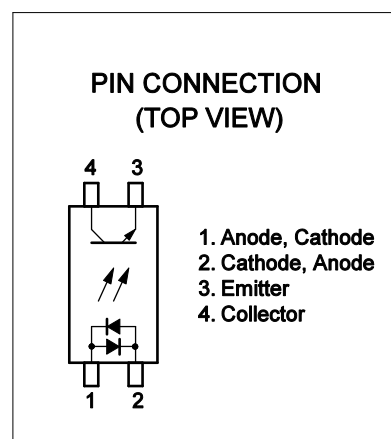
An ultra small flat-lead package has been provided which realizes a reduction in mounting area of about 30%, compared with the PS28xx series.

FEATURES

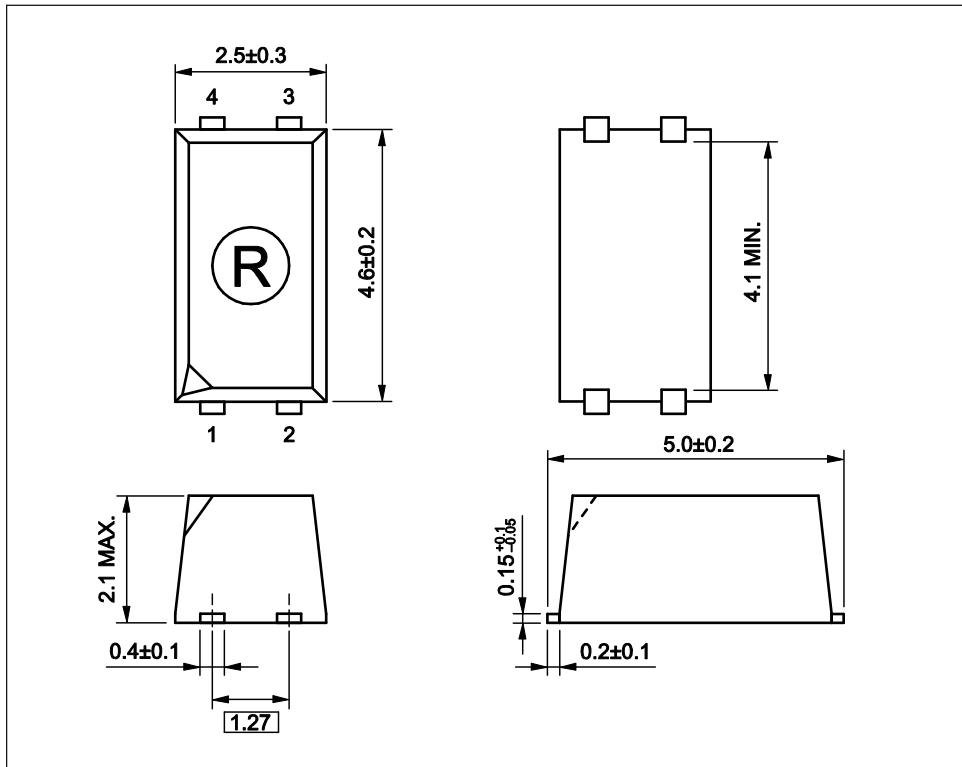
- Ultra small flat-lead package (4.6 (L) × 2.5 (W) × 2.1 (H) mm)
- High current transfer ratio (CTR = 200% TYP. @ $I_F = \pm 1$ mA, $V_{CE} = 5$ V)
- High isolation voltage (BV = 2 500 Vr.m.s.)
- Ordering number of taping product: PS2915-1-F3, 3 500 pcs/reel
- Safety standards
 - UL approved: UL1577, Single protection
 - BSI approved: BS EN 62368-1, Supplementary insulation
 - VDE approved: DIN EN 60747-5-5 (Option)

APPLICATIONS

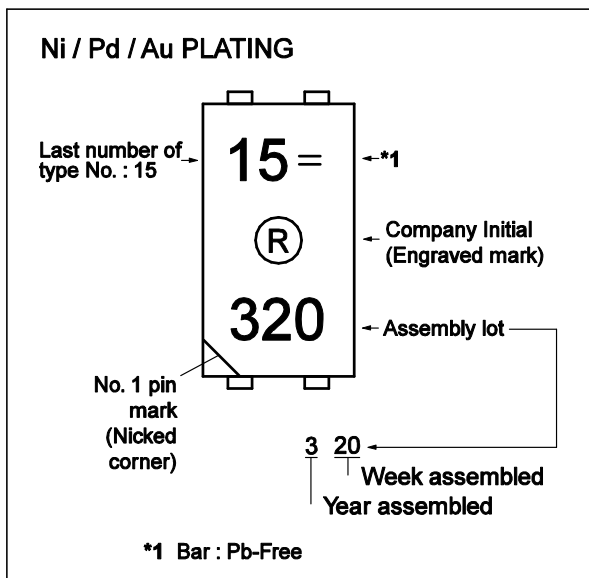
- DC/DC converter
- Modem/PC card



PACKAGE DIMENSIONS (UNIT: mm)



MARKING EXAMPLE



PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	4 mm
Creepage Distance	4 mm
Isolation Distance	0.4 mm

ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS2915-1	PS2915-1-AX	Pb-Free (Ni/Pd/Au)	50 pcs (Tape 50 pcs cut)	Standard products (UL, BSI approved)	PS2915-1
PS2915-1-F3	PS2915-1-F3-AX		Embossed Tape 3 500 pcs/reel		
PS2915-1-V	PS2915-1-V-AX		50 pcs (Tape 50 pcs cut)	UL, BSI, DIN EN 60747-5-5 approved	
PS2915-1-V-F3	PS2915-1-V-F3-AX		Embossed Tape 3 500 pcs/reel		

Note: ^{*1}. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	I_F	± 50	mA
	Forward Current Derating	$\Delta I_F/^\circ\text{C}$	0.5	mA/ $^\circ\text{C}$
	Peak Forward Current ^{*1}	I_{FP}	± 0.5	A
	Power Dissipation	P_D	60	mW
Transistor	Collector to Emitter Voltage	V_{CEO}	40	V
	Emitter to Collector Voltage	V_{ECO}	5	V
	Collector Current	I_C	40	mA
	Power Dissipation Derating	$\Delta P_C/^\circ\text{C}$	1.2	mW/ $^\circ\text{C}$
	Power Dissipation	P_C	120	mW
Isolation Voltage ^{*2}		BV	2 500	Vr.m.s.
Total Power Dissipation		P_T	160	mW
Operating Ambient Temperature		T_A	-55 to +100	$^\circ\text{C}$
Storage Temperature		T_{stg}	-55 to +150	$^\circ\text{C}$

Notes: ^{*1}. $PW = 100 \mu\text{s}$, Duty Cycle = 1%

^{*2}. AC voltage for 1 minute at $T_A = 25^\circ\text{C}$, RH = 60% between input and output
Pins 1-2 shorted together, 3-4 shorted together.

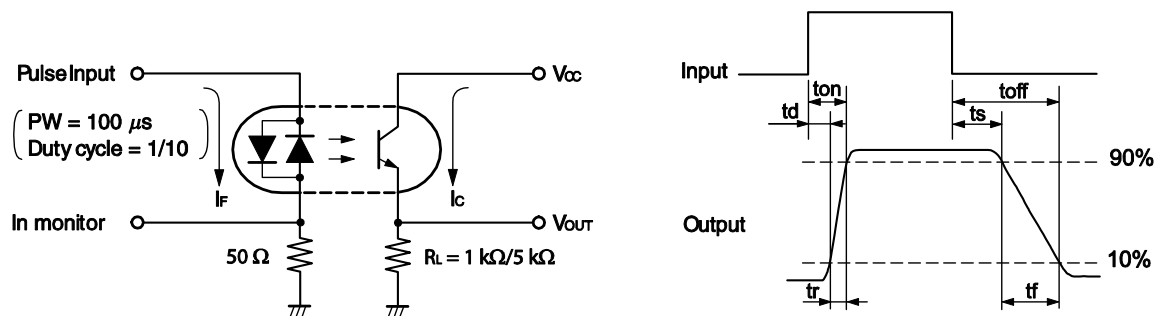
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = ±1 mA	0.9	1.1	1.3	V
	Terminal Capacitance	C _t	V = 0 V, f = 1 MHz		30		pF
Transistor	Collector to Emitter Dark Current	I _{CEO}	I _F = 0 mA, V _{CE} = 40 V			100	nA
Coupled	Current Transfer Ratio (I _C /I _F)* ¹	CTR	I _F = ±1 mA, V _{CE} = 5 V	100	200	400	%
	Collector Saturation Voltage	V _{CE(sat)}	I _F = ±1 mA, I _C = 0.2 mA		0.13	0.3	V
	Isolation Resistance	R _{I-O}	V _{I-O} = 1 kVDC	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time* ²	t _r	V _{CC} = 5 V, I _C = 2 mA, R _L = 1 kΩ		5		μs
	Fall Time* ²	t _f			10		
	Turn-on Time* ²	t _{on}	V _{CC} = 5 V, I _F = ±1 mA, R _L = 5 kΩ		40		μs
	Storage Time* ²	t _s			10		μs
	Turn-off Time* ²	t _{off}			120		μs

Notes: *1 CTR rank

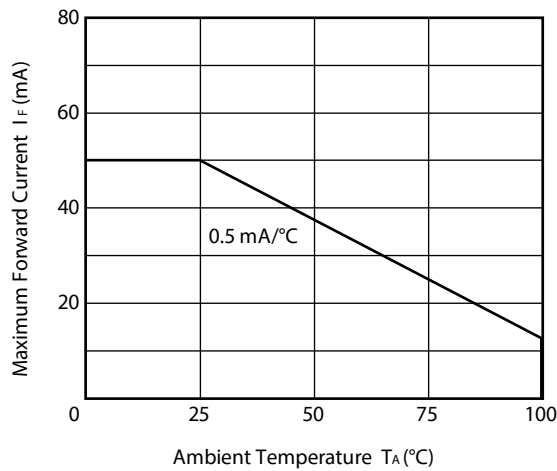
N : 100 to 400 (%)

*2 Test circuit for switching time

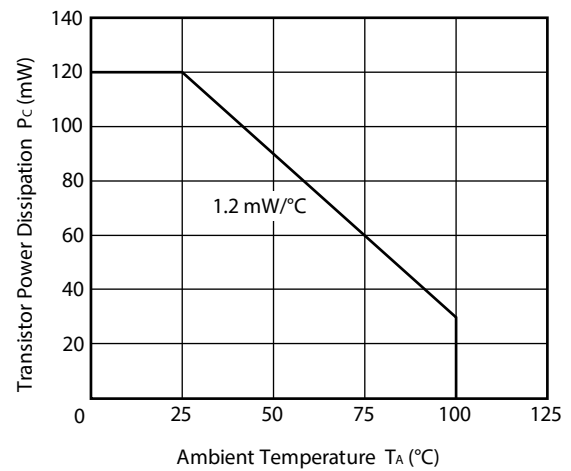


TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

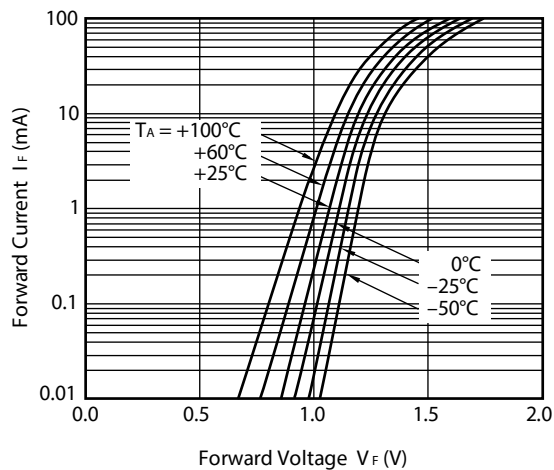
MAXIMUM FORWARD CURRENT vs.
AMBIENT TEMPERATURE



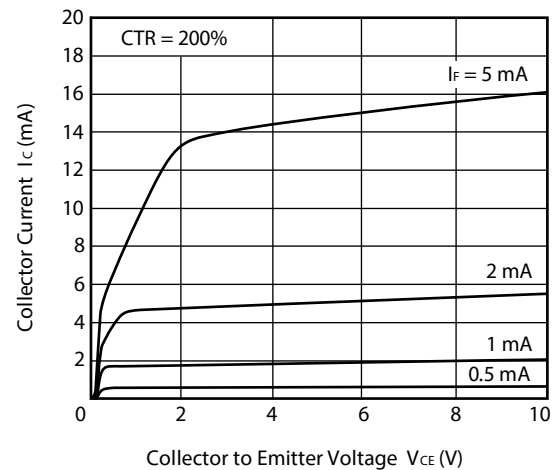
TRANSISTOR POWER DISSIPATION
vs. AMBIENT TEMPERATURE



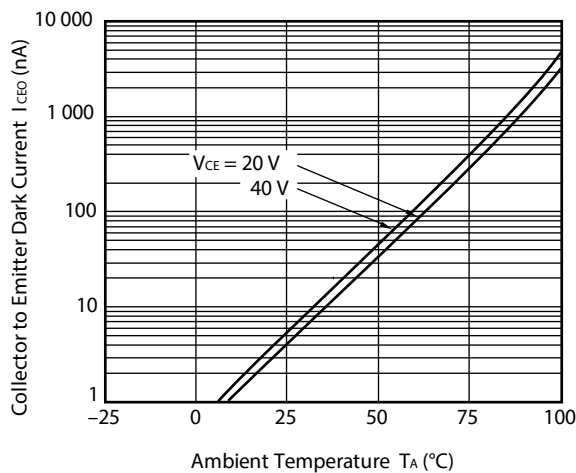
FORWARD CURRENT vs.
FORWARD VOLTAGE



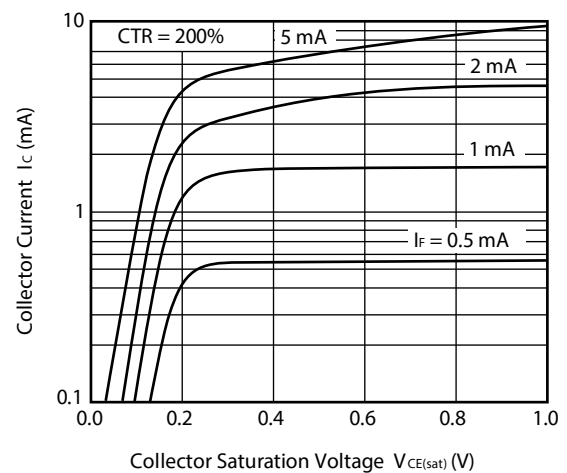
COLLECTOR CURRENT vs.
COLLECTOR TO EMITTER VOLTAGE



COLLECTOR TO EMITTER DARK
CURRENT vs. AMBIENT TEMPERATURE

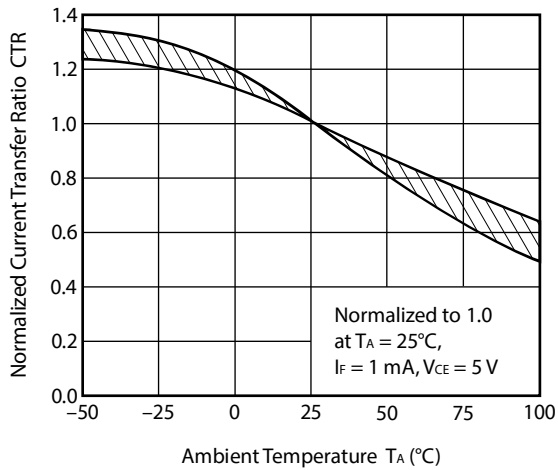


COLLECTOR CURRENT vs.
COLLECTOR SATURATION VOLTAGE

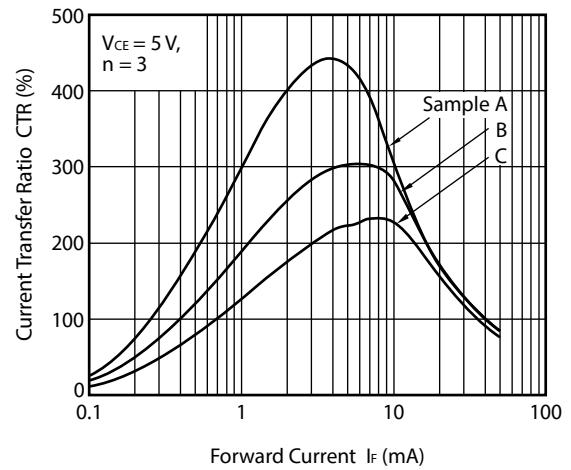


Remark The graphs indicate nominal characteristics.

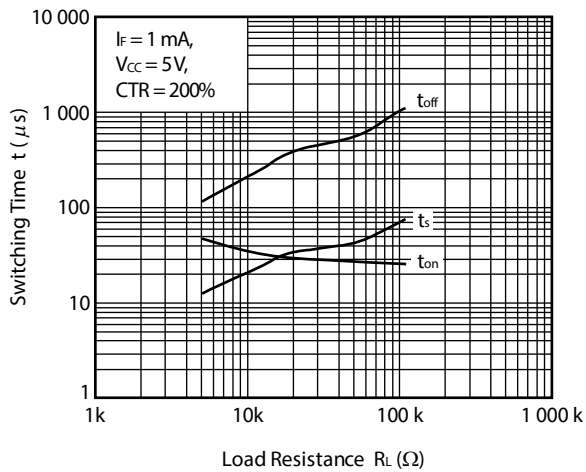
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



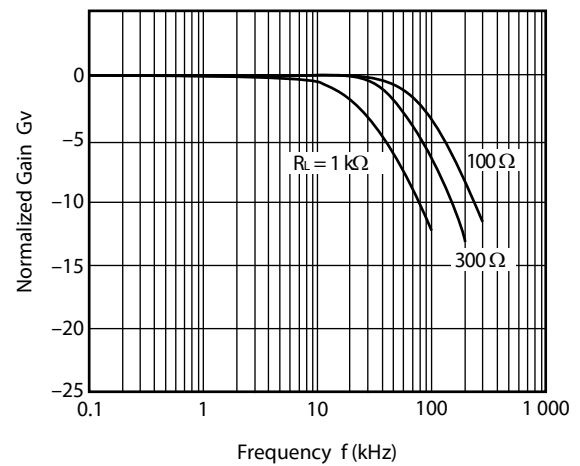
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



SWITCHING TIME vs. LOAD RESISTANCE



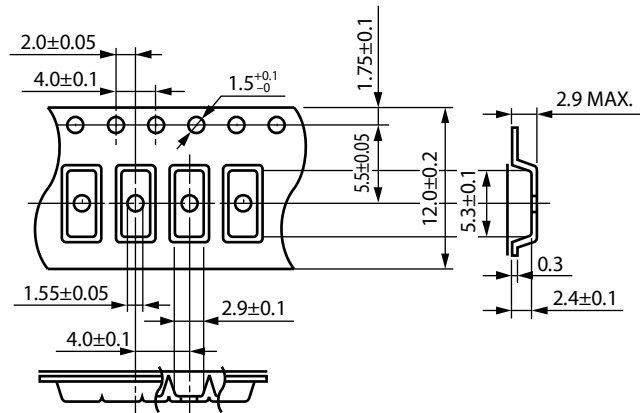
FREQUENCY RESPONSE



Remark The graphs indicate nominal characteristics.

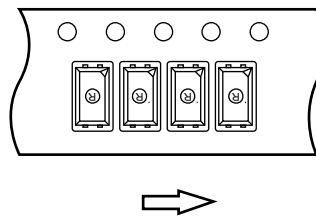
TAPING SPECIFICATIONS (UNIT: mm)

Outline and Dimensions (Tape)

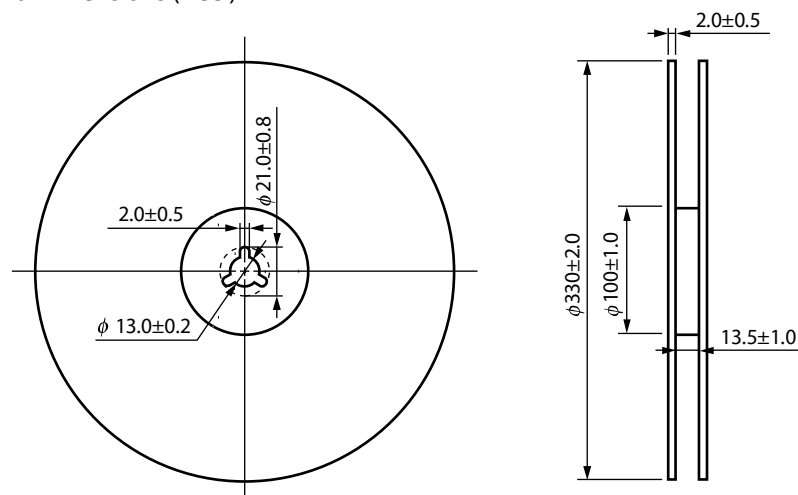


Tape Direction

PS2915-1-F3

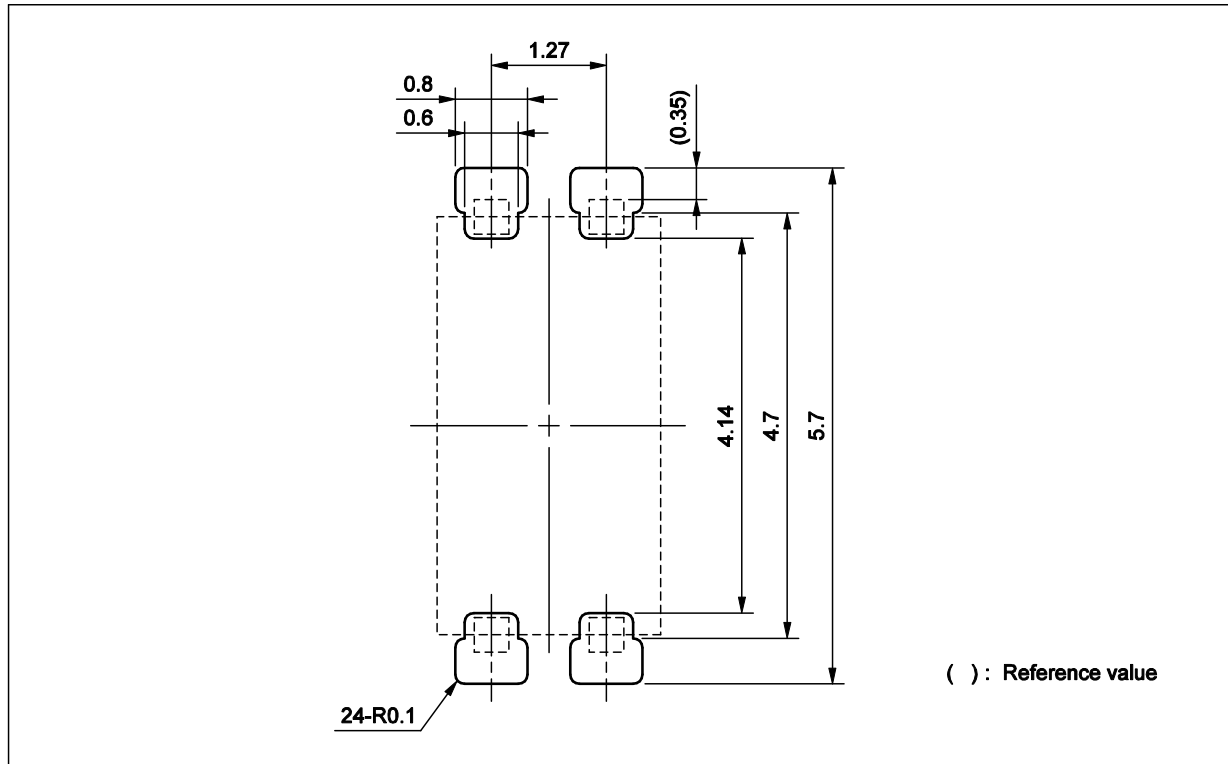


Outline and Dimensions (Reel)



Packing: 3 500 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark This drawing is considered to meet air and outer creepage distance 4.0 mm minimum. All dimensions in this figure must be evaluated before use.

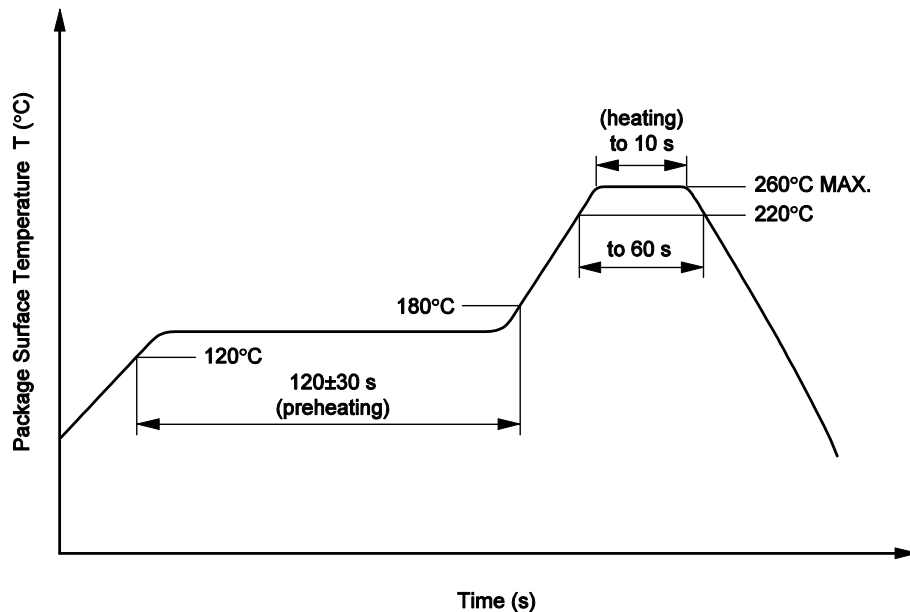
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- | | |
|---|--|
| • Peak reflow temperature | 260°C or below (package surface temperature) |
| • Time of peak reflow temperature | 10 seconds or less |
| • Time of temperature higher than 220°C | 60 seconds or less |
| • Time to preheat temperature from 120 to 180°C | 120 ± 30 s |
| • Number of reflows | Three |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- | | |
|-------------------------|--|
| • Temperature | 260°C or below (molten solder temperature) |
| • Time | 10 seconds or less |
| • Preheating conditions | 120°C or below (package surface temperature) |
| • Number of times | One (Allowed to be dipped in solder including plastic mold portion.) |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

(3) Soldering by Soldering Iron

- | | |
|--|--|
| • Peak Temperature (lead part temperature) | 350°C or below |
| • Time (each pins) | 3 seconds or less |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(4) Cautions

- Flux Cleaning
Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
- Do not use fixing agents or coatings containing halogen-based substances.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

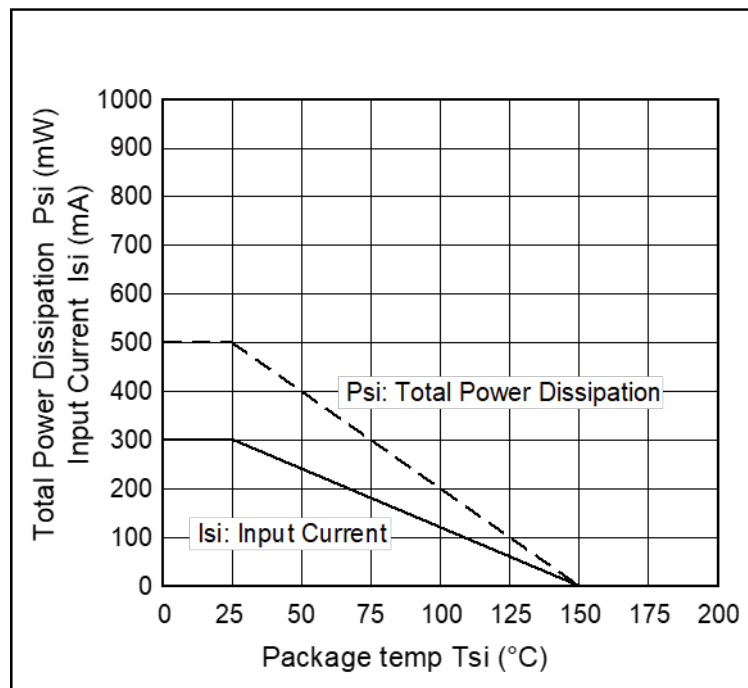
USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

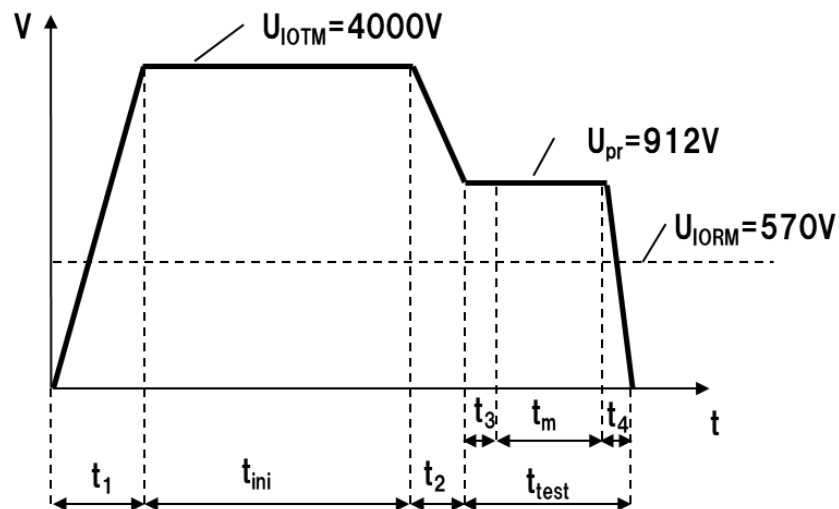
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength			
maximum operating isolation voltage	U_{IORM}	570	V_{peak}
Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.6 \times U_{IORM.}, P_d < 5 \text{ pC}$	U_{pr}	912	V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM.}, P_d < 5 \text{ pC}$	U_{pr}	1068	V_{peak}
Highest permissible overvoltage	U_{TR}	4 000	V_{peak}
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	T_{stg}	-55 to +150	°C
Operating temperature range	T_A	-55 to +100	°C
Isolation resistance, minimum value $V_{IO} = 500 \text{ V dc at } T_A = 25^\circ\text{C}$	$R_{is \text{ MIN.}}$	10^{12}	Ω
$V_{IO} = 500 \text{ V dc at } T_A \text{ MAX. at least } 100^\circ\text{C}$	$R_{is \text{ MIN.}}$	10^{11}	Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve)			
Package temperature	T_{si}	150	°C
Current (input current I_F , $\Psi_i = 0$)	I_{si}	300	mA
Power (output or total power dissipation)	Ψ_i	500	mW
Isolation resistance $V_{IO} = 500 \text{ V dc at } T_A = T_{si}$	$R_{is \text{ MIN.}}$	10^9	Ω

Dependence of maximum safety ratings with package temperature



Method a) Destructive Test, Type and Sample Test



$t_1, t_2 = 1$ to 10 sec

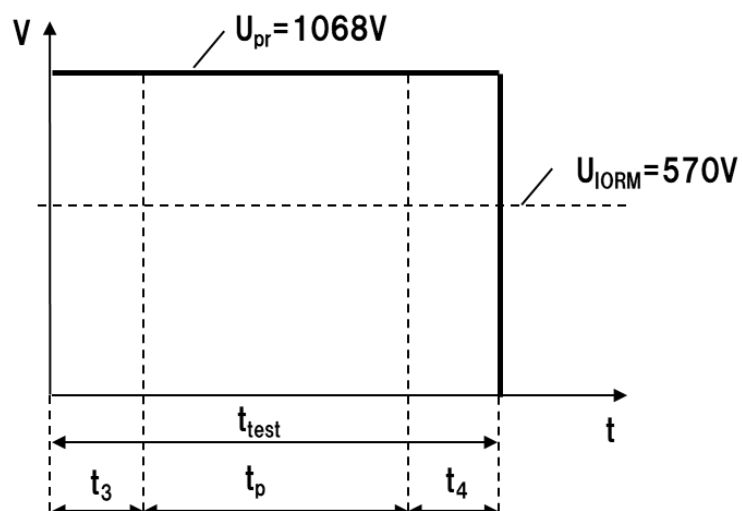
$t_3, t_4 = 1$ sec

t_m (PARTIAL DISCHARGE) = 10 sec

$t_{test} = 12$ sec

$t_{ini} = 60$ sec

Method b) Non-destructive Test, 100% Production Test



$t_3, t_4 = 0.1$ sec

t_p (PARTIAL DISCHARGE) = 1.0 sec

$t_{test} = 1.2$ sec

Caution	<p>GaAs Products</p>	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none">• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.• Do not burn, destroy, cut, crush, or chemically dissolve the product.• Do not lick the product or in any way allow it to enter the mouth.
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(Rev.4.0-1 November 2017)



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